

■ Notice (Storage and Operating Condition)

Note the following to prevent poor die bonding and poor wire bonding.

1. Store the capacitors in manufacturer's package in the following conditions without a rapid thermal change in an indoor room.
 - Temperature: -10 to 40°C
 - Humidity: 30 to 70%RH
2. Avoid storing the capacitors in the following conditions.
 - (a) Ambient air containing corrosive gas. (Chlorine gas, Hydrogen sulfide gas, Ammonia gas, Sulfuric acid gas, Nitric oxide gas, etc.)
 - (b) Ambient air containing volatile or combustible gas
 - (c) In environments with high concentration of airborne particles
 - (d) In liquid (water, oil, chemical solution, organic solvents, etc.)
 - (e) In environments where condensation may occur
 - (f) In direct sunlight
 - (g) In freezing environments

■ Notice (Soldering and Mounting)

1. Die bonding of substrate

(1) Using materials and bonding conditions

- Solders: Au -20%Sn
- Bonding temperature: 300 to 320°C
- Bonding time: less than 1 minute
- Bonding atmosphere: N₂ atmosphere

(2) Notice

- (a) Please scrub the capacitors while mounting.
- (b) Die bonding condition is affected by what kind of solder and base substrate is used. Please evaluate die bonding condition in advance with the same materials as mass production materials and make sure that there is no effect, especially cracking of the ceramics.

2. Wire Bonding

(1) Using materials and bonding conditions

- Wire lead: 25 microns diameter gold wire
- Bonding temperature: 150 to 250°C
- Bonding methods: Thermocompression or thermosonic bonding

(2) Notice

Please do not bond closer than 25 microns from the edge of the electrode.

PLEASE CONTACT US BEFORE USING OUR PRODUCTS IN OTHER BONDING CONDITIONS NOT LISTED ABOVE.

■ Notice (Handling)

Do not directly touch capacitors with bare hands to prevent poor die bonding and poor wire bonding.